

**Changes Made:**

**Quality improvement to GMX272 GenJ PCB layout**

- **Change to TDK multilayer inductors, remove wirewound and laser cut inductors and change all inductor pads to standard 0603 footprint**
- **Change transponder coil to encapsulated (snap-in) coil to improve robustness**
- **Move C18 close to transponder coil as per other GenJ designs**
- **Increase ground clearance around roll switch to reduce heat dissipation and improve soldering**
- **Increase ground clearance around battery tags to reduce heat dissipation and improve soldering**

**No changes have been made to the battery or battery tags**

**No changes have been made to the enclosure**